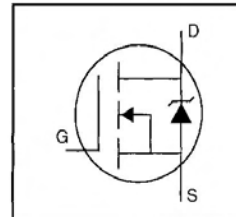


IRLR120PbF IRLU120PbF

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Surface Mount (IRLR120)
- Straight Lead (IRLU120)
- Available in Tape & Reel
- Logic-Level Gate Drive
- R_{DS(on)} Specified at V_{GS}=4V & 5V
- Lead-Free

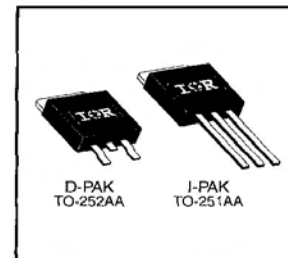


$V_{DSS} = 100V$
$R_{DS(on)} = 0.27\Omega$
$I_D = 7.7A$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D-Pak is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead version (IRFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.



Absolute Maximum Ratings

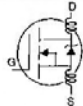
	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, V _{GS} @ 5.0 V	7.7	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, V _{GS} @ 5.0 V	4.9	
I_{DM}	Pulsed Drain Current ①	31	
$P_D @ T_C = 25^\circ C$	Power Dissipation	42	W
$P_D @ T_A = 25^\circ C$	Power Dissipation (PCB Mount)**	2.5	
	Linear Derating Factor	0.33	
	Linear Derating Factor (PCB Mount)**	0.020	W/°C
V _{GS}	Gate-to-Source Voltage	±10	V
E _{AS}	Single Pulse Avalanche Energy ②	210	mJ
I _{AR}	Avalanche Current ①	7.7	A
E _{AR}	Repetitive Avalanche Energy ①	4.2	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns
T _J , T _{STG}	Junction and Storage Temperature Range	-55 to +150	°C
	Soldering Temperature, for 10 seconds	260 (1.6mm from case)	

Thermal Resistance

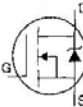
	Parameter	Min.	Typ.	Max.	Units
R _{θJC}	Junction-to-Case	—	—	3.0	°C/W
R _{θJA}	Junction-to-Ambient (PCB mount)**	—	—	50	
R _{θJA}	Junction-to-Ambient	—	—	110	

** When mounted on 1" square PCB (FR-4 or G-10 Material).

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS}=0V, I_D=250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.13	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D=1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.27	Ω	$V_{GS}=5.0V, I_D=4.6A$ ④
		—	—	0.38		$V_{GS}=4.0V, I_D=3.9A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	1.0	—	2.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
g_{fs}	Forward Transconductance	4.4	—	—	S	$V_{DS}=50V, I_D=4.6A$ ④
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{DS}=100V, V_{GS}=0V$
		—	—	250		$V_{DS}=80V, V_{GS}=0V, T_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS}=10V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS}=-10V$
Q_g	Total Gate Charge	—	—	12	nC	$I_D=9.2A$
Q_{gs}	Gate-to-Source Charge	—	—	3.0		$V_{DS}=80V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	7.1		$V_{GS}=5.0V$ See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	9.8	—	ns	$V_{DD}=50V$
t_r	Rise Time	—	64	—		$I_D=9.2A$
$t_{d(off)}$	Turn-Off Delay Time	—	21	—		$R_G=9.0\Omega$
t_f	Fall Time	—	27	—		$R_D=5.2\Omega$ See Figure 10 ④
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	490	—	pF	$V_{GS}=0V$
C_{oss}	Output Capacitance	—	150	—		$V_{DS}=25V$
C_{rss}	Reverse Transfer Capacitance	—	30	—		$f=1.0\text{MHz}$ See Figure 5

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	7.7	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	31		
V_{SD}	Diode Forward Voltage	—	—	2.5	V	$T_J=25^\circ\text{C}, I_S=7.7A, V_{GS}=0V$ ④
t_{rr}	Reverse Recovery Time	—	110	140	ns	$T_J=25^\circ\text{C}, I_F=9.2A$
Q_{rr}	Reverse Recovery Charge	—	0.80	1.0	μC	$di/dt=100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)
- ② $V_{DD}=25V$, starting $T_J=25^\circ\text{C}$, $L=5.3\text{mH}$, $R_G=25\Omega$, $I_{AS}=7.7A$ (See Figure 12)
- ③ $I_{SD}\leq 9.2A$, $di/dt\leq 110A/\mu s$, $V_{DD}\leq V_{(BR)DSS}$, $T_J\leq 150^\circ\text{C}$
- ④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

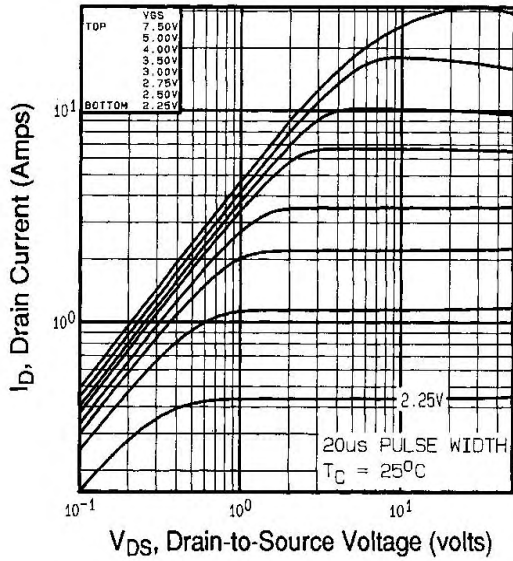


Fig 1. Typical Output Characteristics,
 $T_C=25^\circ C$

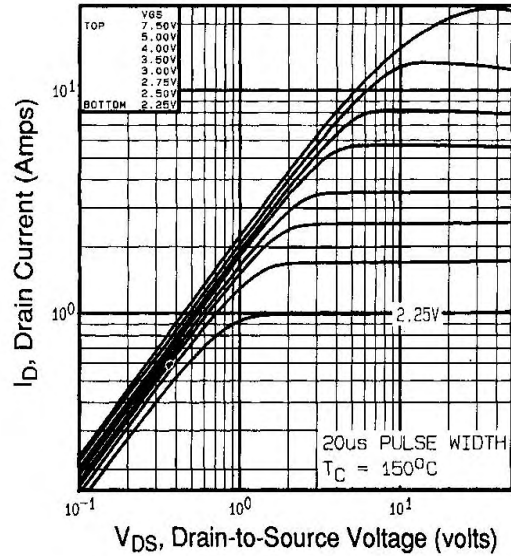


Fig 2. Typical Output Characteristics,
 $T_C=150^\circ C$

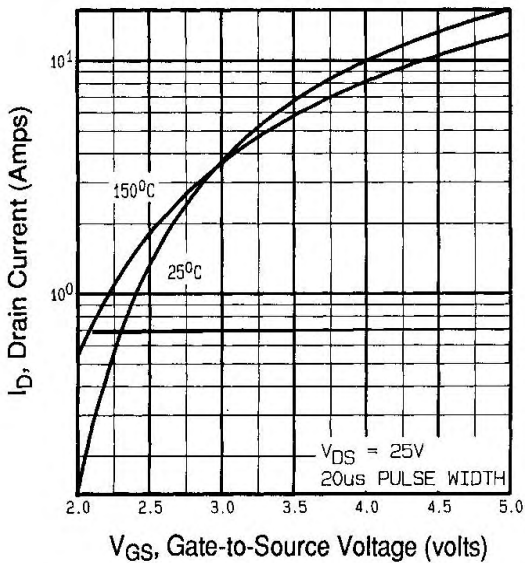


Fig 3. Typical Transfer Characteristics

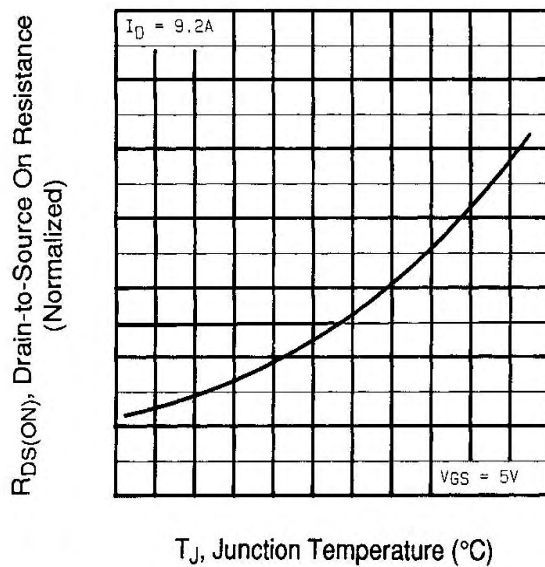


Fig 4. Normalized On-Resistance
Vs. Temperature

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IR Rectifier

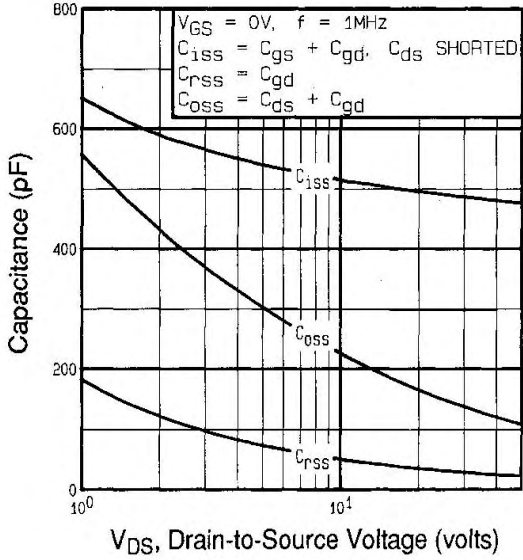


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

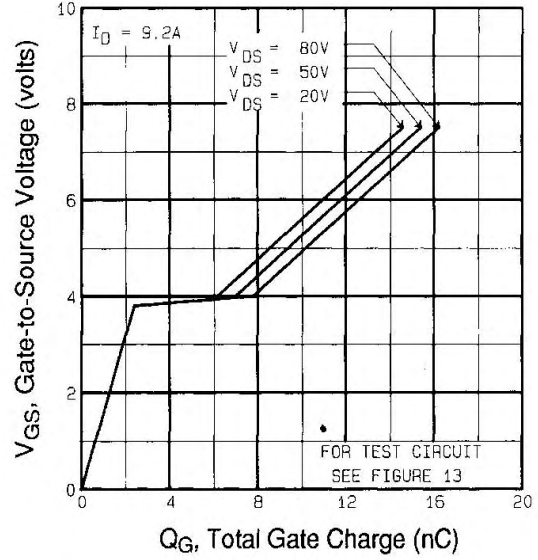


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

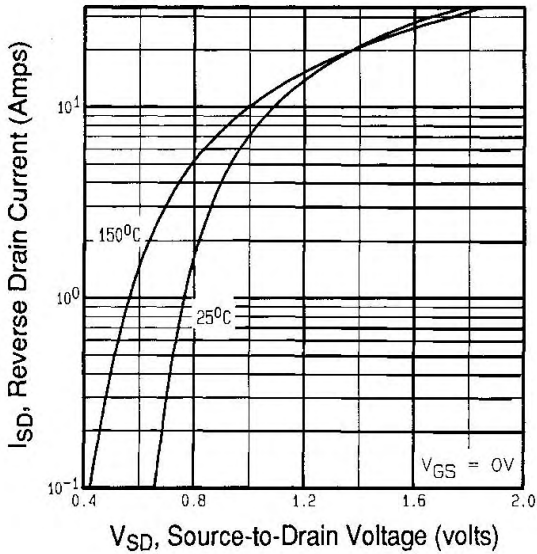


Fig 7. Typical Source-Drain Diode Forward Voltage

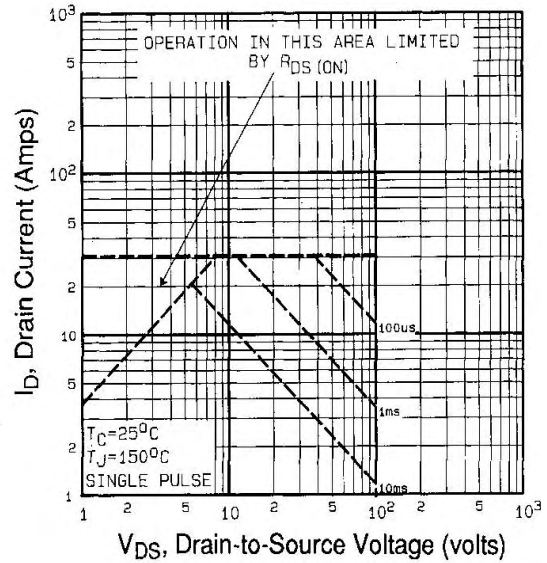


Fig 8. Maximum Safe Operating Area

IRLR/U120PbF

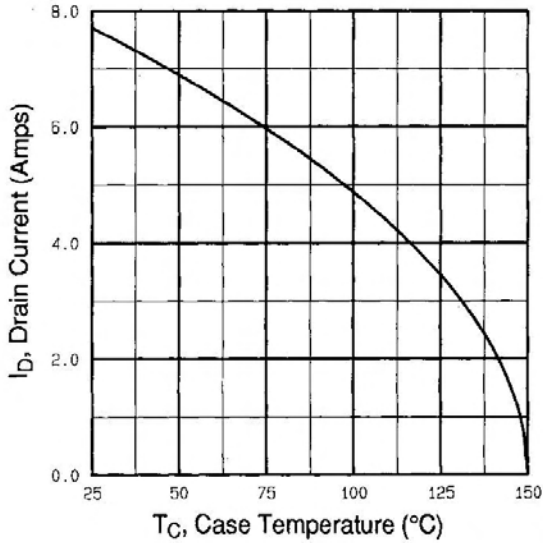


Fig 9. Maximum Drain Current Vs. Case Temperature

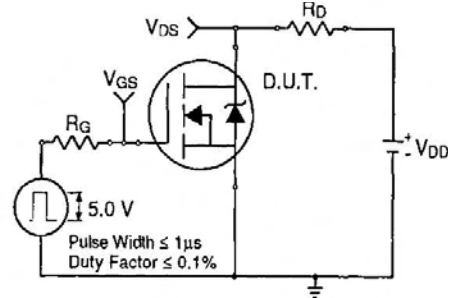


Fig 10a. Switching Time Test Circuit

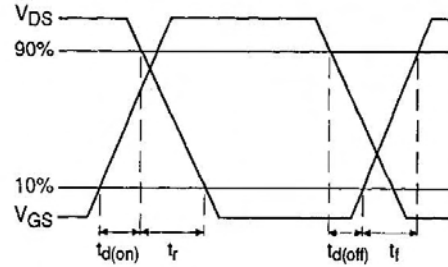


Fig 10b. Switching Time Waveforms

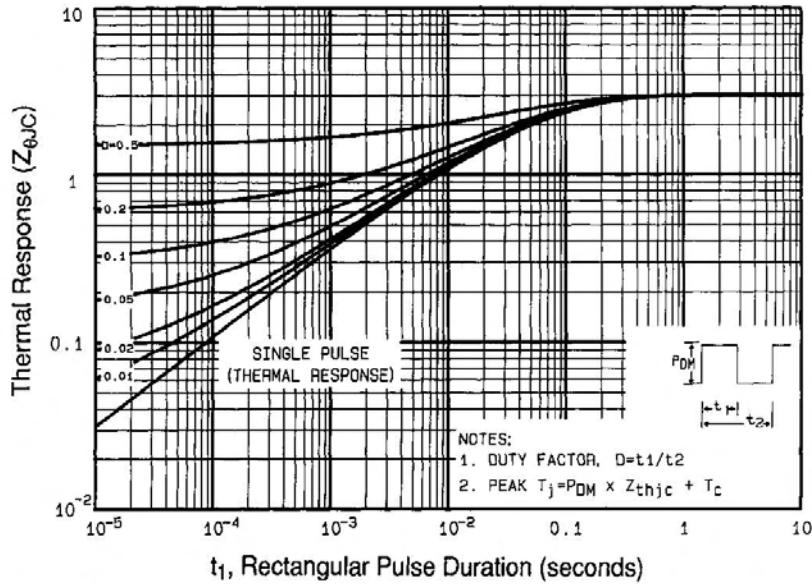


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

IRLR/U120PbF

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IR Rectifier

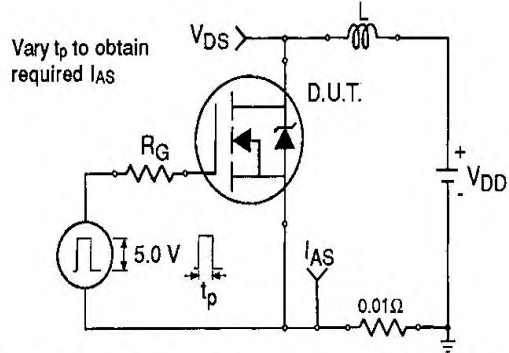


Fig 12a. Unclamped Inductive Test Circuit

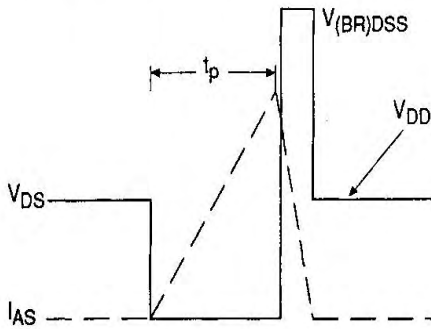


Fig 12b. Unclamped Inductive Waveforms

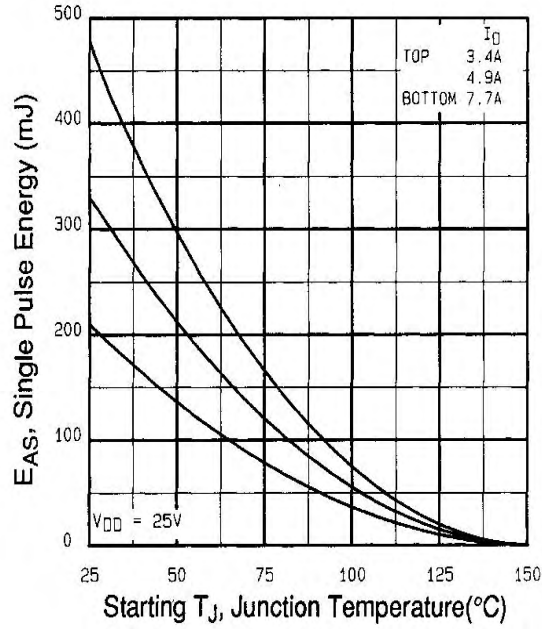


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

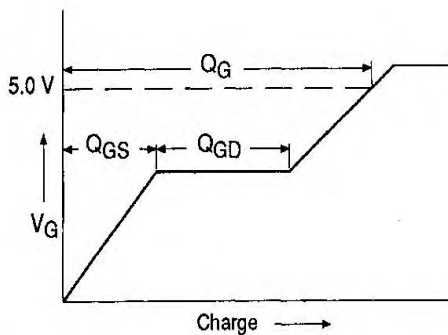


Fig 13a. Basic Gate Charge Waveform

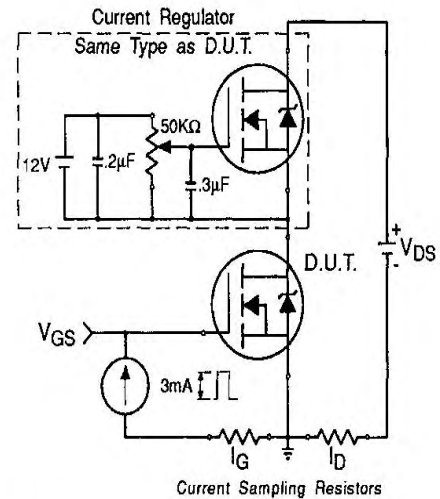


Fig 13b. Gate Charge Test Circuit

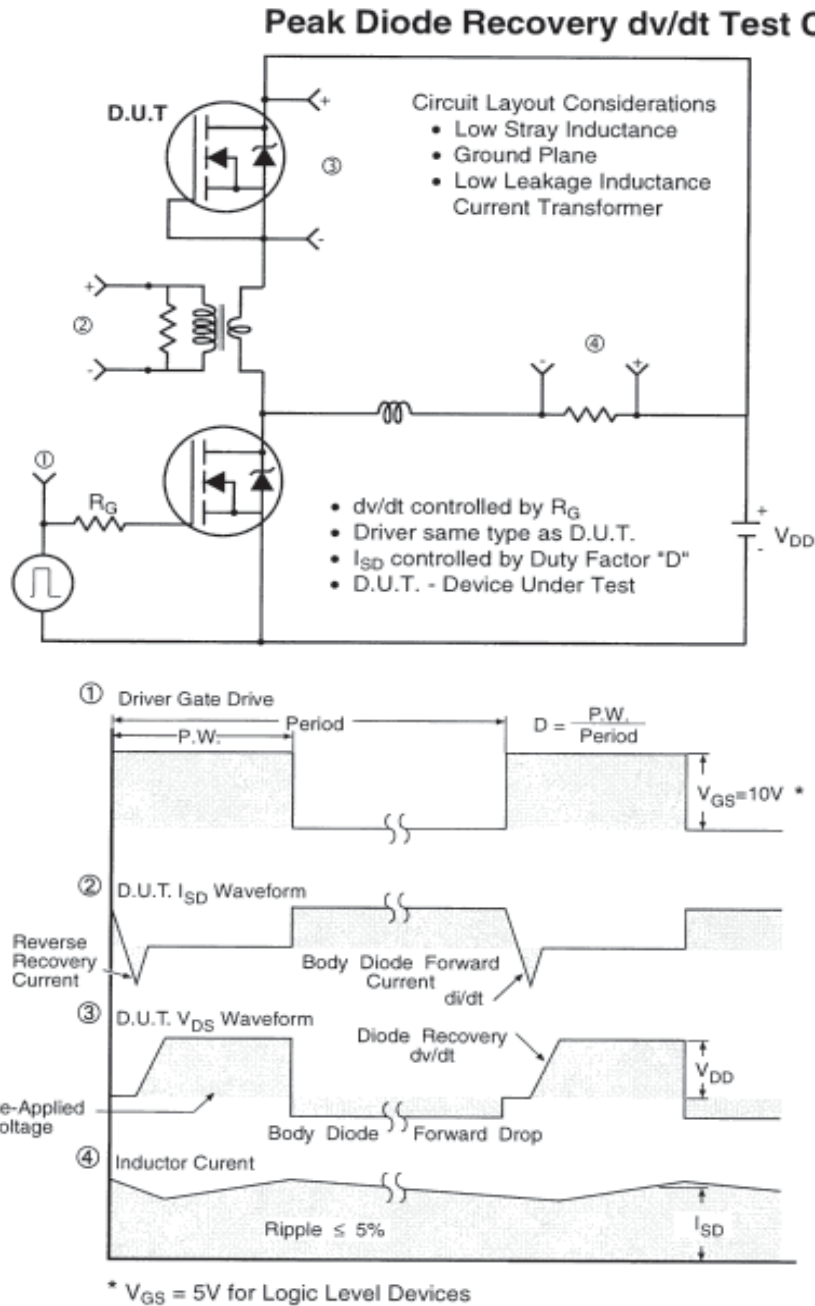


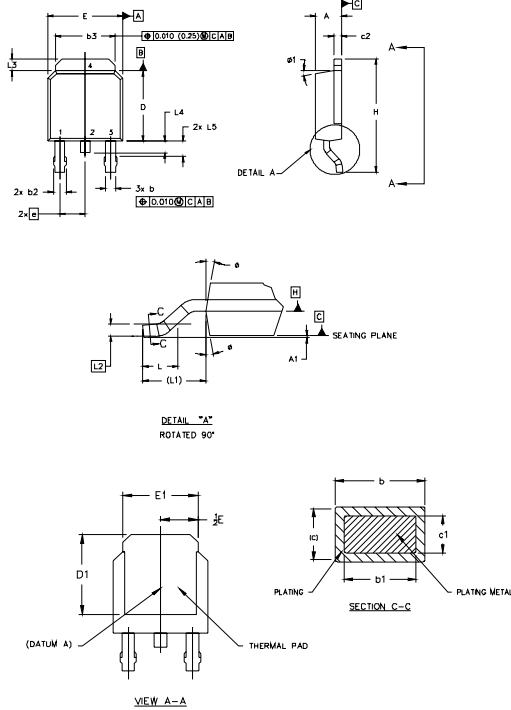
Fig 14. For N-Channel HEXFETS

IRLR/U120PbF

International
IR Rectifier

D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- 2.0 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- 3.0 LEAD DIMENSION UNCONTROLLED IN L5.
- 4.0 DIMENSION D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.0 SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 [0.127] AND .010 [0.254] FROM THE LEAD TIP.
- 6.0 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 7.0 OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
A	2.18	2.39	.086	.094	
A1		0.15		.005	
b	0.64	0.89	.025	.035	
b1	0.64	0.79	.025	0.031	
b2	0.76	1.14	.030	.045	
b3	4.35	5.46	.195	.215	
c	0.46	0.61	.018	.024	
c1	0.41	0.56	.016	.022	
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	
D1	5.21	-	.205	-	
E	6.35	6.73	.250	.265	
E1	4.32	-	.170	-	
e	2.29		.090 BSC		
H	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2.74 BSC		.108 REF.		
L2	0.251 BSC		.020 BSC		
L3	0.89	1.27	.035	.050	
L4		1.02		.040	
L5	1.14	1.52	.045	.060	
a	0"	10"	0"	10"	
a1	0"	15"	0"	15"	

LEAD ASSIGNMENTS

HEXFEEET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

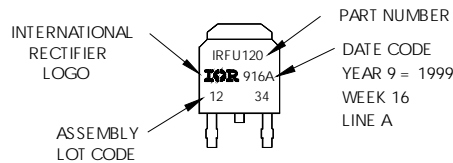
IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

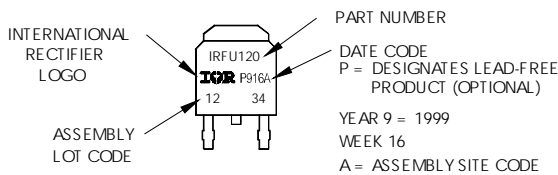
D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 1234
ASSEMBLED ON WW 16, 1999
IN THE ASSEMBLY LINE "A"

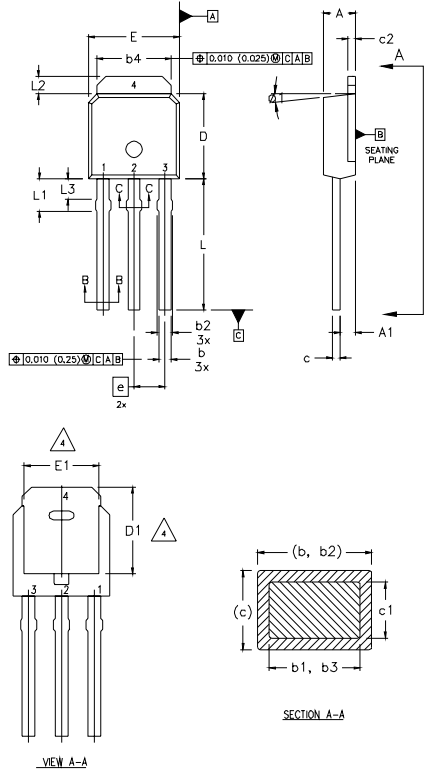
Note: "P" in assembly line position
indicates "Lead-Free"



OR



I-Pak (TO-251AA) Package Outline (Dimensions are shown in millimeters (inches))



- NOTES:
- 1 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
 - 2 DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
 - 3 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 - 4 THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.
 - 5 LEAD DIMENSION UNCONTROLLED IN L3.
 - 6 DIMENSION b1, b3 APPLY TO BASE METAL ONLY.
 - 7 OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA.
 - 8 CONTROLLING DIMENSION : INCHES.

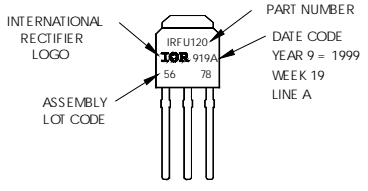
LEAD ASSIGNMENTS

- HEXFEEET
- 1.- GATE
 - 2.- DRAIN
 - 3.- SOURCE
 - 4.- DRAIN

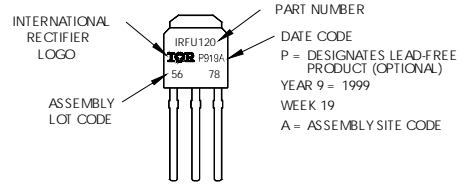
SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	.094	
A1	0.89	1.14	0.035	0.045	
b	0.64	0.89	0.025	0.035	
b1	0.64	0.79	0.025	0.031	4
b2	0.76	1.14	0.030	0.045	
b3	0.76	1.04	0.030	0.041	
b4	5.00	5.46	0.195	0.215	4
c	0.46	0.61	0.018	0.024	
c1	0.41	0.56	0.016	0.022	
c2	.046	0.86	0.018	0.035	
D	5.97	6.22	0.235	0.245	3, 4
D1	5.21	-	0.205	-	4
E	6.35	6.73	0.250	0.265	3, 4
E1	4.32	-	0.170	-	4
e	2.29		0.090 BSC		
L	8.89	9.60	0.350	0.380	
L1	1.91	2.29	0.075	0.090	
L2	0.89	1.27	0.035	0.050	4
L3	1.14	1.52	0.045	0.060	5
ø1	0"	15"	0"	15"	

I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRLR120 WITH ASSEMBLY LOT CODE 5678 ASSEMBLED ON WW19, 1999 IN THE ASSEMBLY LINE "A"
Note: "P" in assembly line position indicates "Lead-Free"



OR

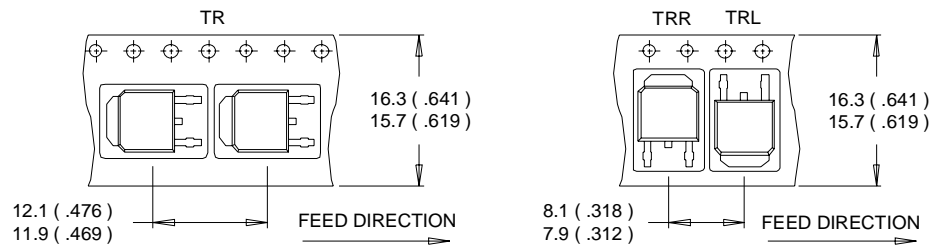


IRLR/U120PbF

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IR Rectifier

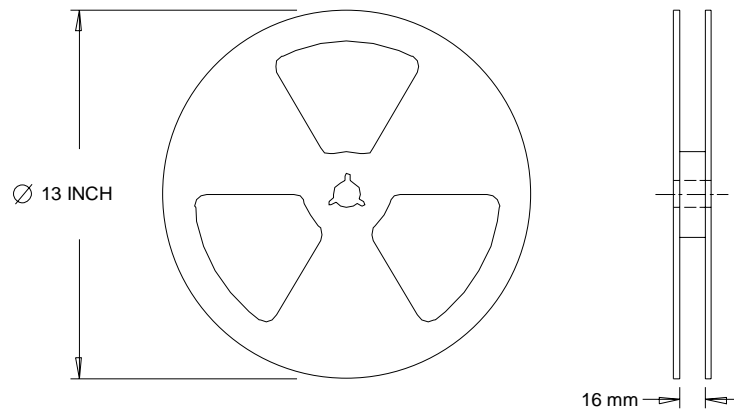
D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.

International
IR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

TAC Fax: (310) 252-7903

Visit us at www.irf.com for sales contact information. 12/04

www.irf.com